

## **AMENDMENTS**

### **In The Drawings**

Please replace the original FIG. 1 with the amended one that is marked with red ink.

### **In The Specification**

Please amend paragraphs [0020] and [0021] as follows:

**[0020]** The current conduction structure 114 includes a plurality of serially connected metallic layers 104a, 104b, 104c each located at a different height level between the bonding pad layer 116 and the substrate 100. The conductive metallic layers 104a, 104b, 104c are linked together via plugs 110a and 110b, respectively. The conductive metallic layer 104c and the bonding pad layer 116 are linked together via plugs 110c. The conductive metallic layer 104a is in contact with the substrate 100 so that the current conduction structure 114 actually connects the bonding pad layer 116 and the substrate 100 together. The conductive metallic layers 104a, 104b, 104c connect electrically with a signal line (not shown). Hence, the conductive metallic layers are electrically connected to a device section 118 on the substrate 100. The conductive metallic layers can be local metallic interconnects, for example.

**[0021]** The mechanical support structure 112 is disposed over a non-device section 120, and includes a plurality of serially connected support metallic layers 102a, 102b and 102c, each located at a different height level between the bonding pad layer 116 and the substrate 100. The support metallic layers 102a, 102b, 102c are linked together via plugs 108a and 108b. The support metallic layer 102c and the bonding pad layer 116 are linked together via plugs 108c. The support metallic layer 102a and the substrate 100 are in contact with each other to form the

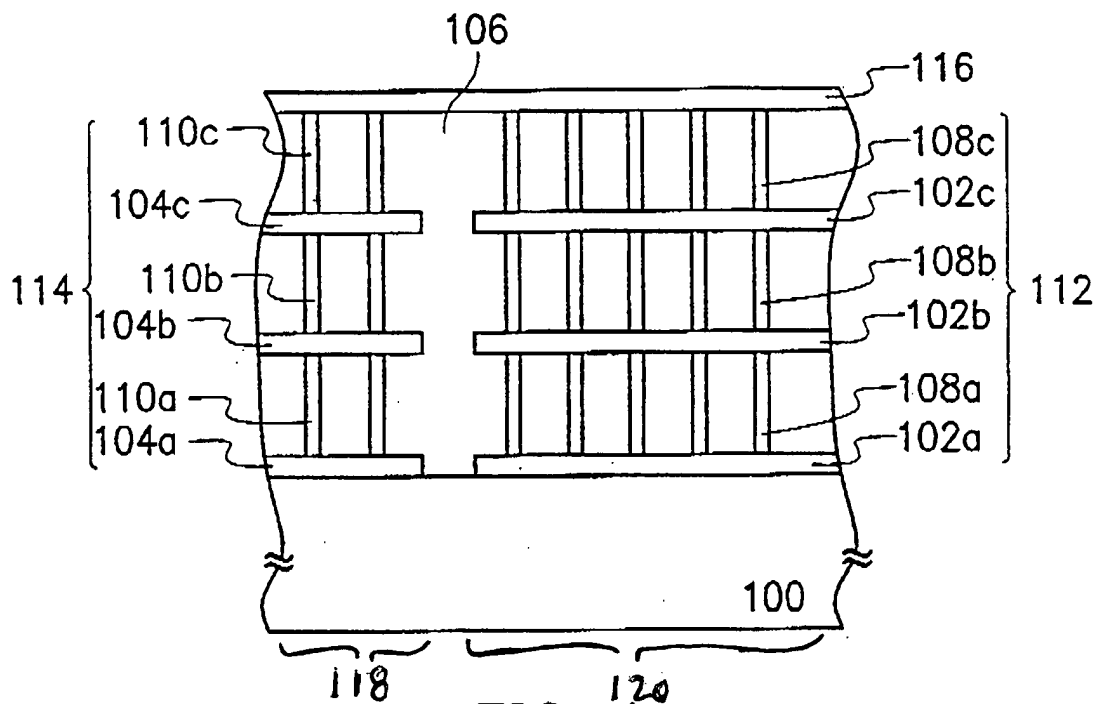


FIG. 1

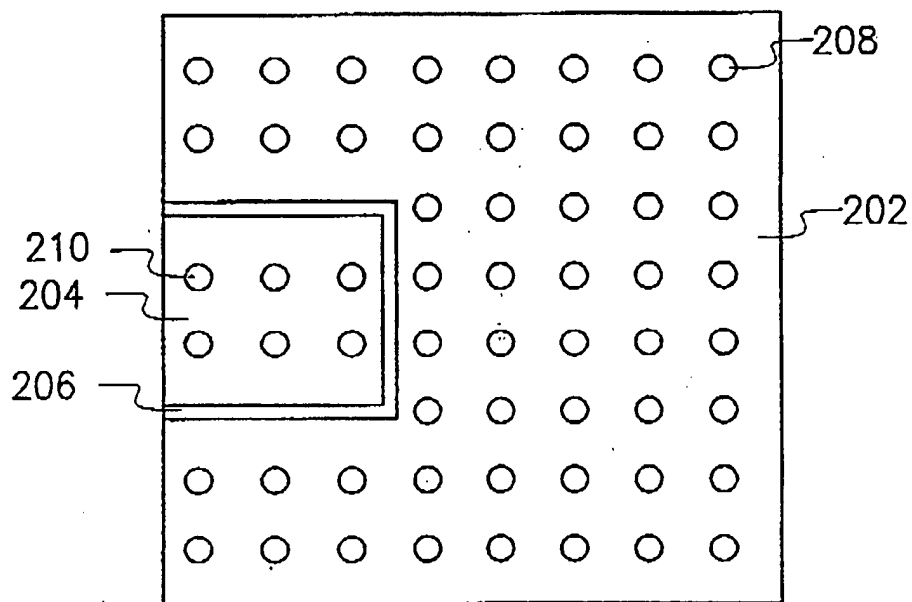


FIG. 2